

IIRW 2022 CALL FOR PAPERS

IEEE INTERNATIONAL INTEGRATED RELIABILITY WORKSHOP

IIRW

IEEE
INTERNATIONAL INTEGRATED
RELIABILITY WORKSHOP

October 9-14, 2022

**Stanford Sierra
Conference Center
Fallen Leaf Lake,
CA, USA**

Abstract Deadline
July 09, 2022

Author Notification
August 31, 2022

Late News Deadline
September 10, 2022

General Chair:
Matthew Hogan
Siemens Digital
Industries Software

TPC Chair:
Francesco Maria Puglisi
University of Modena and
Reggio Emilia

www.iirw.org

The **IEEE International Integrated Reliability Workshop (IIRW)** focuses on ensuring electronic device reliability through fabrication, design, testing, characterization, and simulation, as well as identification of the defects and physical mechanisms responsible for reliability problems.

IIRW 2022: "Reliable electronics for a reliable society"

- Best Student Paper Award
- All accepted papers published in IEEEExplore
- Top 5-7 papers will be extended for publication in IEEE TDMR
- Reliability Experts Forum: Discussion with several panelists among the top reliability experts on the current understanding and challenges on various topics.

Outstanding features of the IIRW are

- Strong plenary, invited, tutorials, and technical program
- Unparalleled opportunities to meet world-leading experts
- Discussion and special interest groups sessions
- Unique rustic and secluded environment

IIRW 2022 welcomes abstracts on, but not limited to, these topics

- **FOCUS AREA:** Circuit reliability, device-circuit degradation, aging
- **FOCUS AREA:** In-memory computing and neuromorphic reliability
- **FOCUS AREA:** Plasma-induced damage, electrostatic discharge
- FEOL/MOL/BEOL dielectrics (high- k , SiO₂, SiON, low- k)
- FET, FinFET, SOI, III-V, SiGe reliability (HCI, BTI, TDDB, RTN, etc.)
- Conventional and emerging memories (Flash, RRAM, etc.)
- Emerging technologies and devices (2D materials, IGZO, etc.)
- Power, wide-bandgap (SiC, GaN, etc.) devices and circuits reliability
- RF and mm/sub-mm Wave devices and circuits reliability
- Modeling and simulation of reliability, including self-heating
- Process integration reliability
- Failure analysis and advanced packaging reliability
- Impact of devices degradation on circuit reliability
- Design-in-reliability (products, circuits, systems, processes)
- Advanced automotive circuits, systems, products reliability
- Customer/manufacturer product reliability requirements
- Wafer-level reliability tests for monitoring and qualification

Two-page abstract with representative data and figures should state clearly the results of your work and why they are significant.

For more information, please visit www.iirw.org, or contact:
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